

Specifications

Insulation Resistance: 1,000M Ω min. at 500V DC
 Dielectric Withstanding Voltage: 700V AC for 1 minute
 Contact Resistance: 30m Ω max. at 10m /20mV max.
 Current Rating: 1A max.
 Operating Temperature Range: -55°C to +170°C
 Mating Cycles: 25,000 insertions min.
 Contact Force: 50g min. per pin at minimum displacement of 0.3mm
 150g max. per pin at maximum displacement of 0.7mm

Part Number (Details)

IC51 - 100 4 - 827

Series No.

No. of Contact Pins

Number of Sides with Contacts

Design Number

Materials and Finish

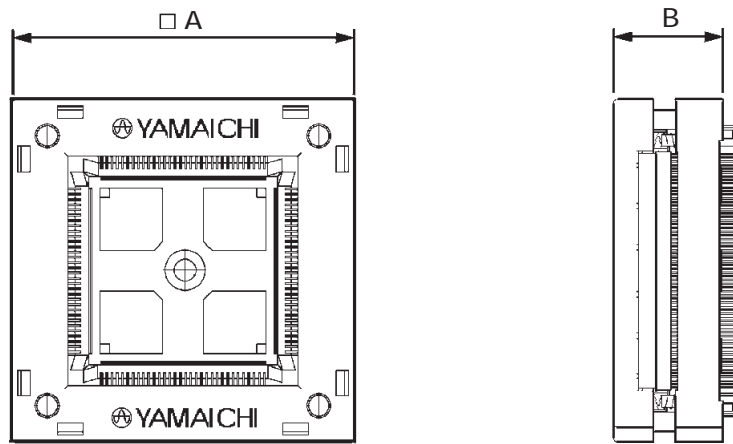
Housing: Polyetherimide (PEI), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel

Features

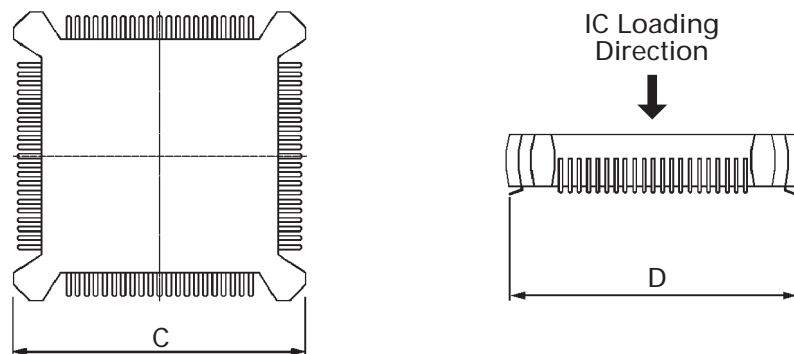
↳ Clamshell socket for BQFP devices

Applicable Socket and IC Dimensions (Reference Only)

Outline Socket Dimensions



Outline IC Dimensions

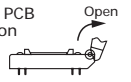


Part Number	Pin Count	Pitch	Socket Dimensions		IC Dimensions	
			A	B	C	D
IC51-1004-827	100	0.635	47.5	34.0	22.86	22.35
IC51-1324-828	132	0.635	53.5	40.0	27.94	27.43
IC51-1644-829	164	0.635	58.0	44.0	32.02	23.51
IC51-1964-1300	196	0.635	64.0	49.0	38.10	37.59

IC51 Series (Clamshell)

Bumper Quad Flat Package (BQFP)

Socket & PCB Orientation



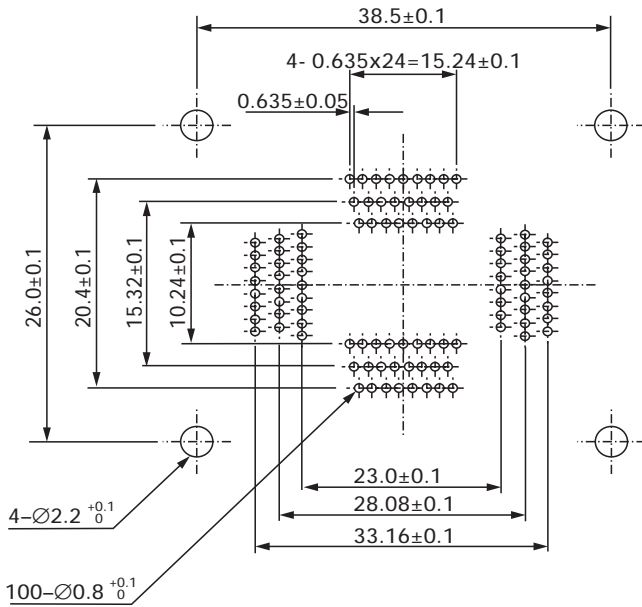
Top View from Socket



Recommended PCB Layouts (100 to 196 pins)

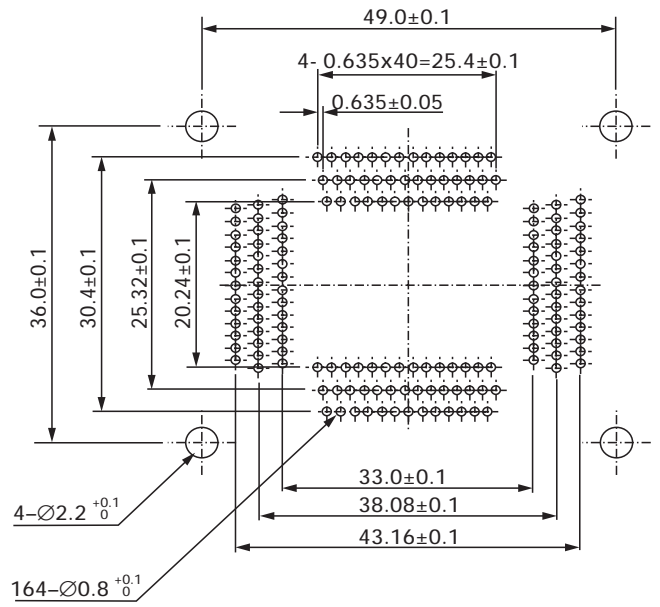
100 pins

IC51-1004-827



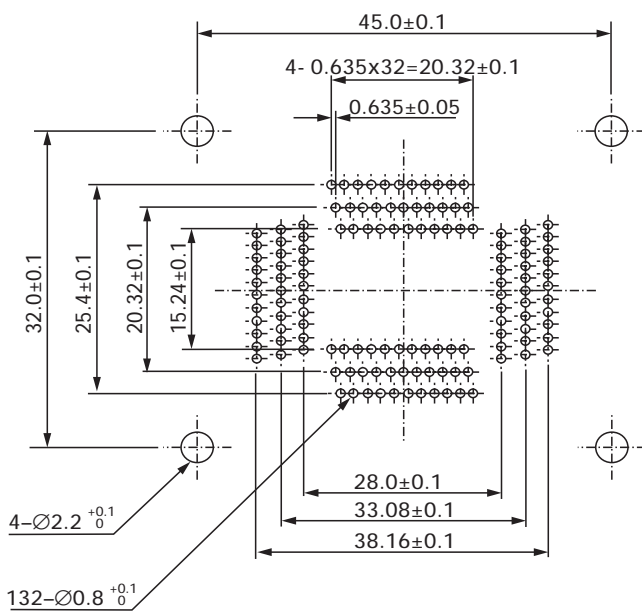
164 pins

IC51-1644-829



132 pins

IC51-1324-828



196 pins

IC51-1964-1300

